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CLAIMS

1. A method of mounting a planar electronic circuit chip on a flexible sheet together with another planer electric element, characterized by steps of:

selecting the another electric element and the electronic circuit chip so that the planar surface of the another electric element is greater than the planar surface of the electronic circuit chip; and

mounting the another electric element and the electronic circuit chip onto the sheet so that the planer surface of the another electronic element and the planar surface of the electronic circuit chip are located in parallel with the surface of the sheet, and the planer surface of the electronic circuit chip is accommodated within the planar surface of the another electric element as viewed in a direction perpendicular to the surface of the sheet.

- 2. A method of mounting an electronic circuit chip onto a foldable sheet, characterized in that the electronic circuit chip is mounted to the sheet so that the electronic circuits chip is prevented from being located at a position where a crease is formed when the sheet is folded.
- 3. A method of mounting a circuit chip on a foldable sheet having a rectangular sheet surface, characterized in that the electronic circuit chip is mounted on the sheet so as to prevent the electronic

circuit chip from being located at least at a position which is obtained by 1/2, 1/3 or 1/4 of the length of longer sides of the sheet surface and which is obtained by 1/2 of short sides of the sheet surface.

- 4. A method of mounting an electronic circuit chip as set forth in claim 2, characterized in that the electronic circuit chip is mounted at a position in the vicinity of an edge of the sheet surface.
- 5. A method of mounting a planer electronic circuit chip on a foldable sheet having a rectangular sheet surface together with another planar electric element, characterized in that setting the planar surface of the another electric element to be slightly smaller than a size of each of rectangular area which are obtained by sectioning the sheet surface by n x m (where n and m are integers larger than 2), and

mounting the another electric element and the electronic circuit chip on the sheet so that the planer surface of the another electric element and the planar surface of the electronic circuit chip are arranged in parallel with the surface of the sheet, and the planar surface of the another electric element is accommodated within one of the rectangular areas which are obtained by sectioning the sheet surface with m x n, as viewed in a direction perpendicular to the sheet surface, and the planer surface of the electronic circuit chip is accommodated within the planar surface of the another electric element as viewed in a direction perpendicular

to the sheet surface.

- 6. A method of mounting an electronic circuit chip as set forth in claim 2, characterized in that a long-rod like or a long planar like electric part is mounted on the sheet so that the longitudinal direction of the electric part is coincident with the sidewise direction of the sheet.
- 7. A method of mounting an electronic circuit chip as set forth in claim 2, characterized in that the sheet is made of paper.
- 8. A method of mounting an electronic circuit chip as set forth in claim 2, characterized in that the sheet is tape-like.
- 9. A method of mounting an electronic circuit chip as set forth in claim 7, characterized in that the sheet has a two layer structure, and the electronic circuit chip is mounted between two layers of the sheet.
- 10. A method of mounting an electronic circuit chip as set forth in claim 7, characterized in that the electronic circuit chip is mounted on the surface of one of two front and rear sheet surfaces of the sheet.
- 11. A planar electric circuit chip mounted on a flexible sheet, characterized in that the electronic circuit chip has a thickness, a length of the long sides thereof, and a bending strength which satisfy:

 $3PL^2 + 6WL + 6M - \sigma H^2 \leq 0$

where a force exerted to the electronic circuit chip is

exhibited by equally distributed loads P (N/m²) per unit area, exerted to the entire planar surface of the electronic circuit chip, and a concentrated load W (N/m) per unit length, is exerted to the free end, in such a case that one of the short sides of the planar surface of the electronic circuit chip is used as a fixed end while the other short side on the opposite side thereof is used as a free end,

where a moment exerted to the electronic circuit chip is exhibited by a moment M (N) per unit length, exerted to the free end in such a case that one of the short sides of the planar surface of the electronic circuit chip is used as a fixed end while the other short side on the opposite side thereof is used as a free end, and

where H (m) is the thickness of the electronic circuit chip;

L (m) is a length of the long sides of the electronic circuit chip; and

 σ (N/m²) is a bending strength of stronger one of a bending strength of the planar another electric element larger than the electronic circuit chip mounted on the planar surface of the another electric element and the bending strength of the electronic circuit chip.

- 12. A sheet mounted thereon with an electronic circuit chip stated in claim 11.
- A foldable sheet having a rectangular sheet

surface and mounted thereon with an electric circuit composed of a planar electric circuit chip, a planar capacitor and an antenna, characterized in that the electronic circuit chip is mounted on the sheet so that it is prevented from being located at a position where a crease is created when the sheet is folded in a predetermined folding method, and the another electric element and the electronic circuit chip are mounted on the sheet so that the planar surface of the another electric element and the planar surface of the electronic circuit chip are in parallel with the sheet surface, the planar surface of the electronic circuit chip is accommodated within the planar surface of the another electric element, as viewed in a direction perpendicular to the surface of the sheet, and the antenna is mounted on the sheet so that the longitudinal direction of the antenna is coincident with the sidewise direction of the sheet.

14. A foldable sheet having a rectangular sheet surface, and mounted thereon with an electric circuit having a planar electronic circuit chip, a planar capacitor and an antenna, characterized in that the planar surface of the capacitor has a size which is slightly smaller than that of each of rectangular areas which are obtained by sectioning the sheet surface with n x m (where n and m are integers larger than 2), and

the capacitor, the electronic circuit chip and the antenna are mounted on the sheet so that the

planar surface of the capacitor and the planar surface of the capacitor are in parallel with the sheet surface, the planar surface of the capacitor is accommodated with one of the rectangular areas obtained by sectioning the sheet surface with n x m, as viewed in a direction perpendicular to the sheet surface, and the planar surface of the electronic circuit part and the contour of the antenna are accommodated within the planar surface of the capacitor as viewed in a direction perpendicular to the sheet surface.